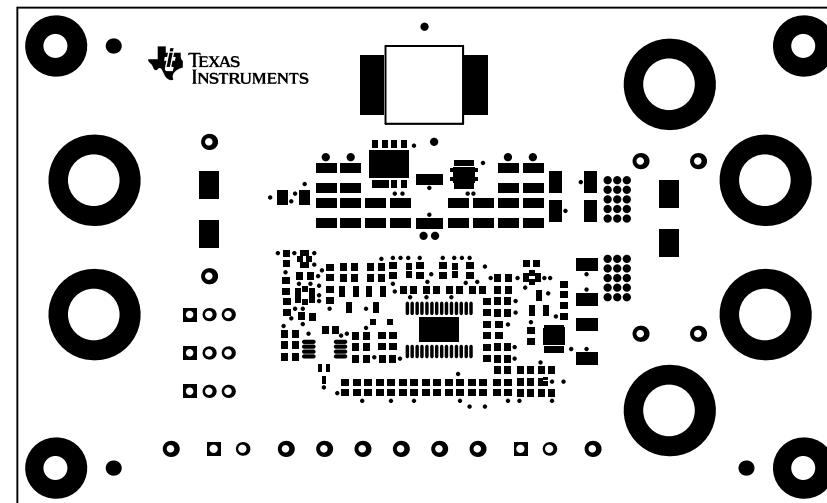
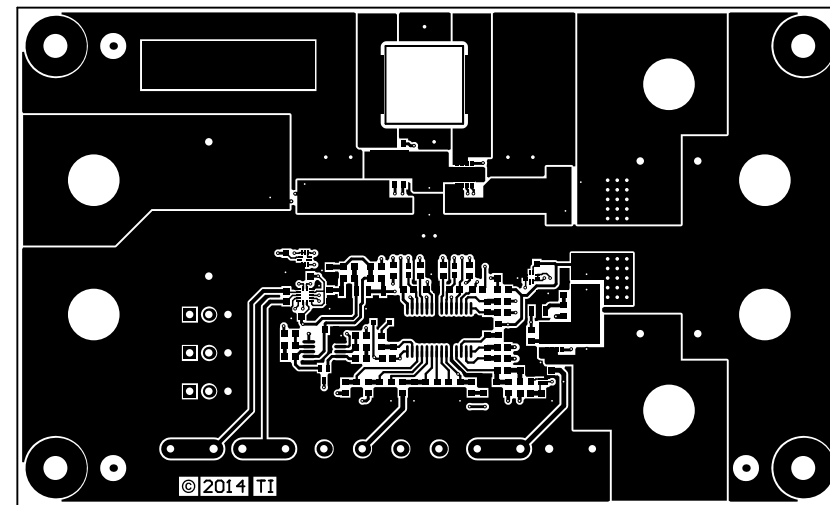


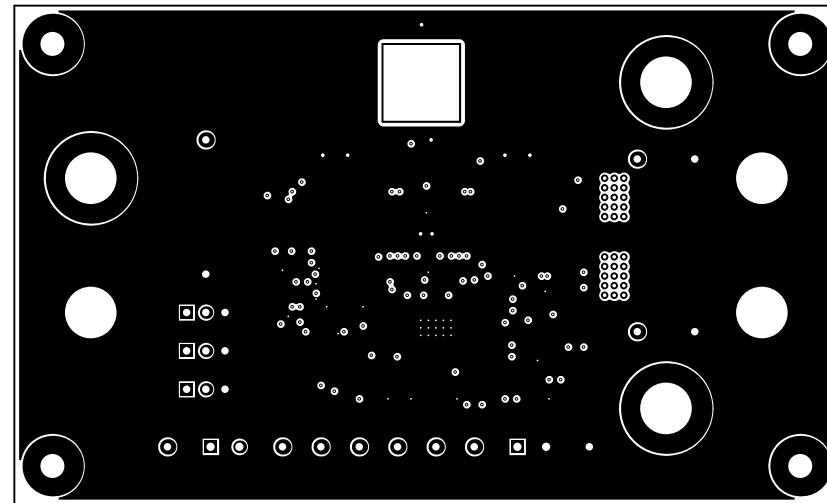
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10594	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 12/24/2014 3:48:11 AM	TEXAS INSTRUMENTS	



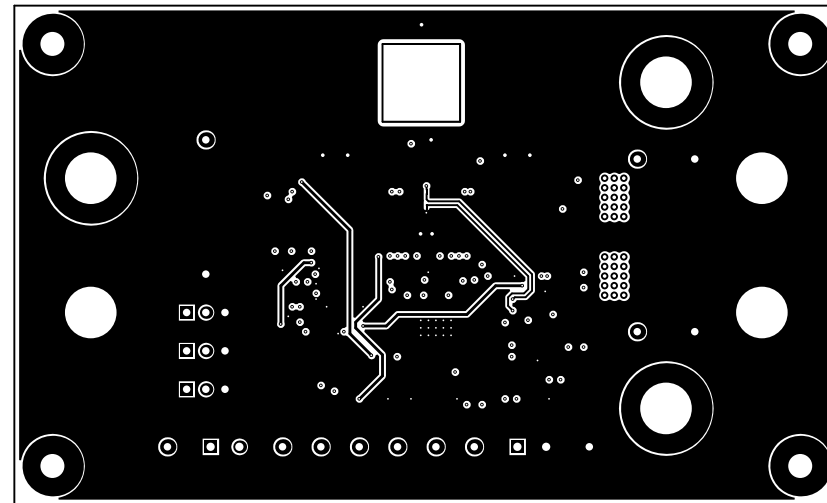
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10594	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 12/24/2014 3:48:12 AM	TEXAS INSTRUMENTS	



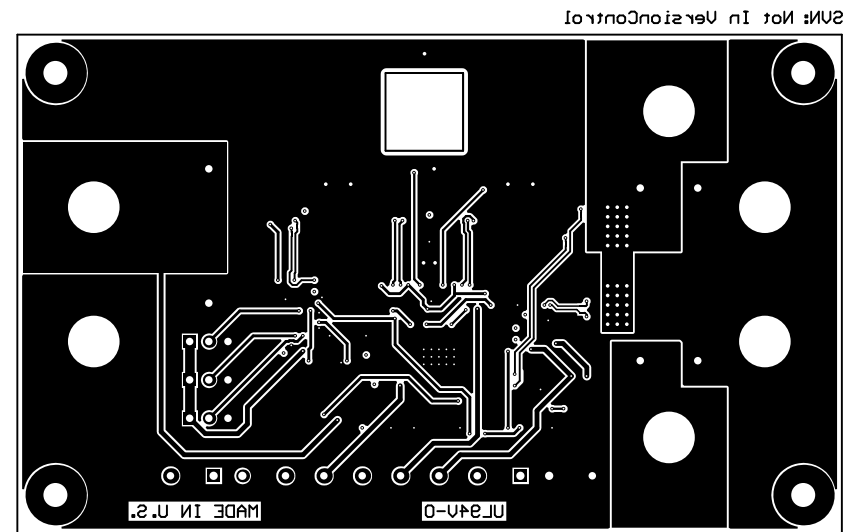
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10594	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 12/24/2014 3:48:13 AM	TEXAS INSTRUMENTS	



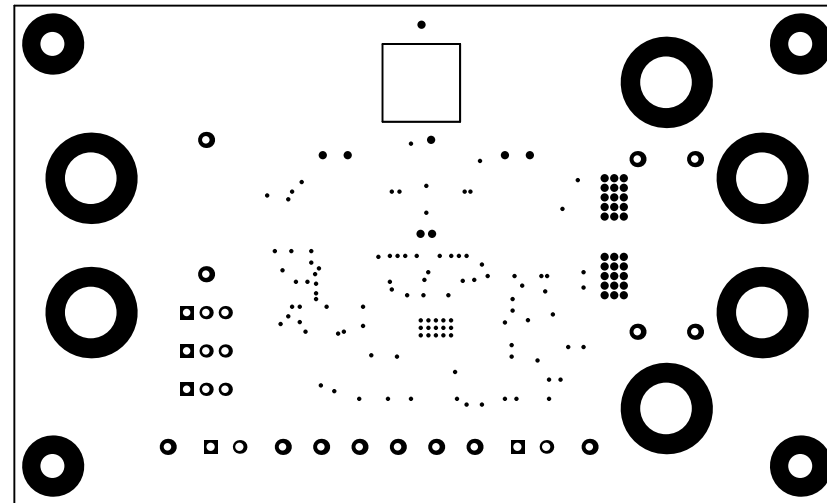
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10594	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer1	GENERATED : 12/24/2014 3:48:14 AM	TEXAS INSTRUMENTS	



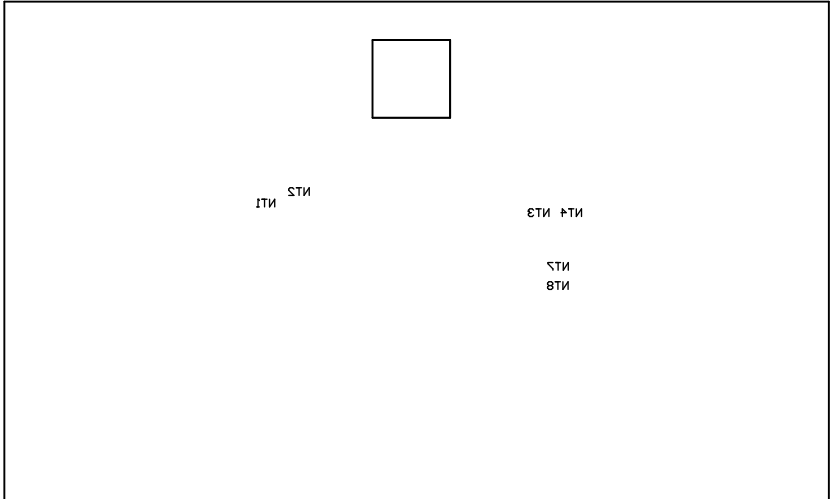
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10594	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer2	GENERATED : 12/24/2014 3:48:15 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10594	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 12/24/2014 3:48:16 AM	TEXAS INSTRUMENTS	

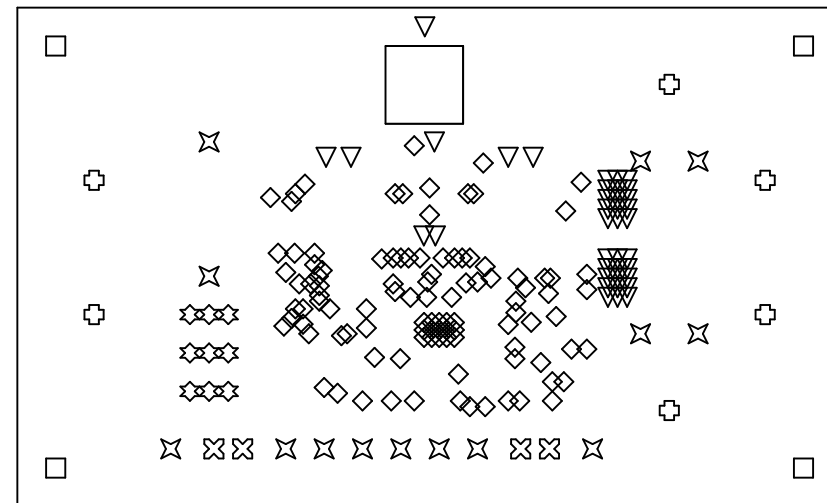


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10594	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 12/24/2014 3:48:17 AM	TEXAS INSTRUMENTS	



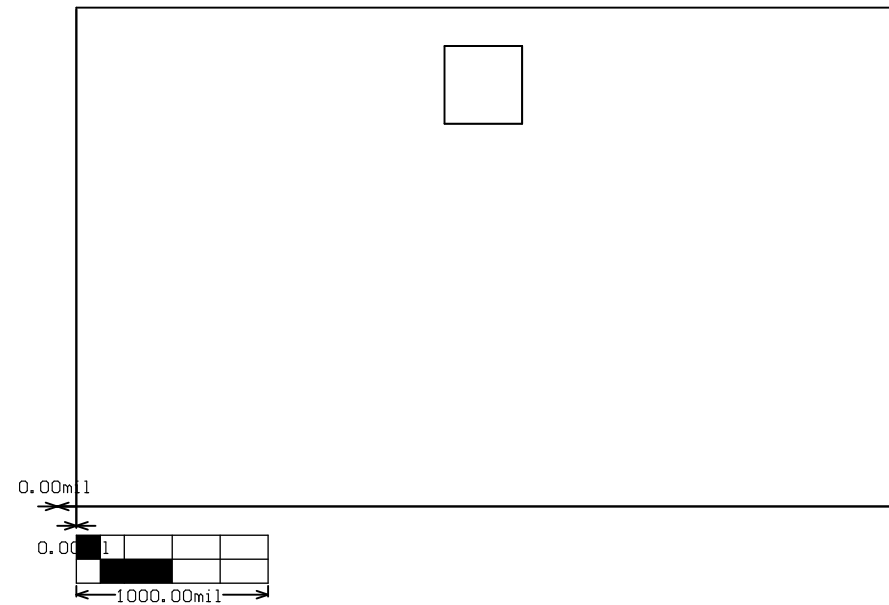
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10594	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 12/24/2014 3:48:18 AM	TEXAS INSTRUMENTS	





Symbol	Quantity	Finished Hole Size	Plated	Hole Type
◇	105	10.00mil (0.254mm)	PTH	Round
▽	38	20.00mil (0.508mm)	PTH	Round
☆	9	39.37mil (1.000mm)	PTH	Round
✕	14	40.00mil (1.016mm)	PTH	Round
⊗	4	43.31mil (1.100mm)	PTH	Round
□	4	125.98mil (3.200mm)	PTH	Round
⊕	6	270.00mil (6.858mm)	PTH	Round
	180 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10594	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 12/24/2014 3:48:19 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10594	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 12/24/2014 3:48:19 AM	TEXAS INSTRUMENTS	

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